

FH8818K

N- Channel Enhancement Mode Power MOSFET

Description

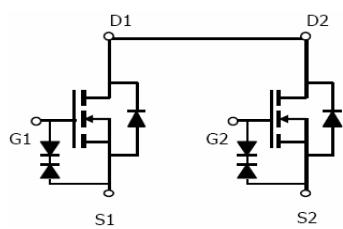
The FH8818K uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected.

Application

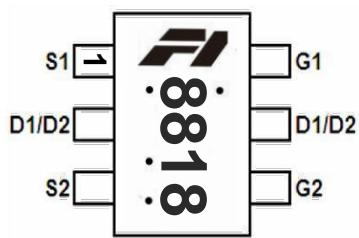
- Uni-directional load switch
- Bi-directional load switch

General Features

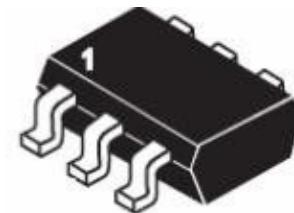
- $V_{DS} = 20V$, $I_D = 6.5A$
- $R_{DS(ON)} < 18 \text{ m}\Omega$ (Typ) @ $V_{GS}=4.5V$
- $R_{DS(ON)} < 18.5 \text{ m}\Omega$ (Typ) @ $V_{GS}=3.7V$
- $R_{DS(ON)} < 19.5 \text{ m}\Omega$ (Typ) @ $V_{GS}=3.1V$
- $R_{DS(ON)} < 21 \text{ m}\Omega$ (Typ) @ $V_{GS}=2.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package
- ESD Rating: 2000V HBM



Schematic diagram



Marking and pin Assignment



SOT23-6 top view

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain Source Voltage	V_{DS}	20	V
Gate Source Voltage	V_{GS}	± 12	V
Drain Current Continuous	I_D	6.5	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	26	A
Maximum Power Dissipation	P_D	1.25	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	100	°C/W
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Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=18\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 10	μA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.45	0.7	1.0	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4.5\text{A}$		18	19.5	$\text{m}\Omega$
		$V_{\text{GS}}=3.7\text{V}, I_{\text{D}}=4\text{A}$	-	18.5	20.5	$\text{m}\Omega$
		$V_{\text{GS}}=3.1\text{V}, I_{\text{D}}=4\text{A}$	-	19.5	22	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=2\text{A}$	-	21	25	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=6\text{A}$	-	35	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$		993		PF
Output Capacitance	C_{oss}		-	210	-	PF
Reverse Transfer Capacitance	C_{rss}			139		PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=10\text{V}, R_{\text{L}}=1.2\Omega$ $V_{\text{GS}}=8\text{V}, R_{\text{GEN}}=3\Omega$	-	2.5		nS
Turn-on Rise Time	t_r		-	7.2		nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	49		nS
Turn Off Fall Time	t_f		-	10.8		nS
Total Gate Charge	Q_g	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=4.5\text{V}$	-	14.2		nC
Gate-Source Charge	Q_{gs}		-	1.5	-	nC
Gate-Drain Charge	Q_{gd}		-	4.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{s}}=1\text{A}$	-	-	1.2	V
Diode Forward Current ^(Note 2)	I_{s}		-	-	3	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

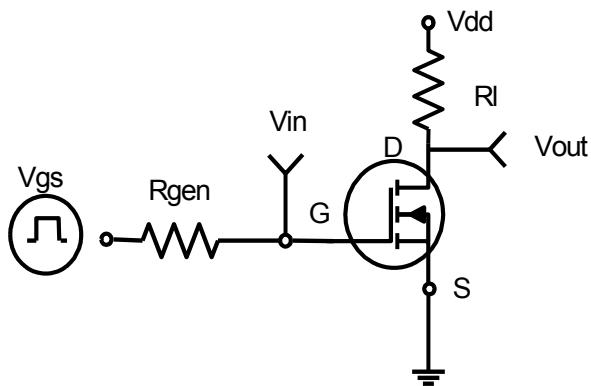


Figure 1:Switching Test Circuit

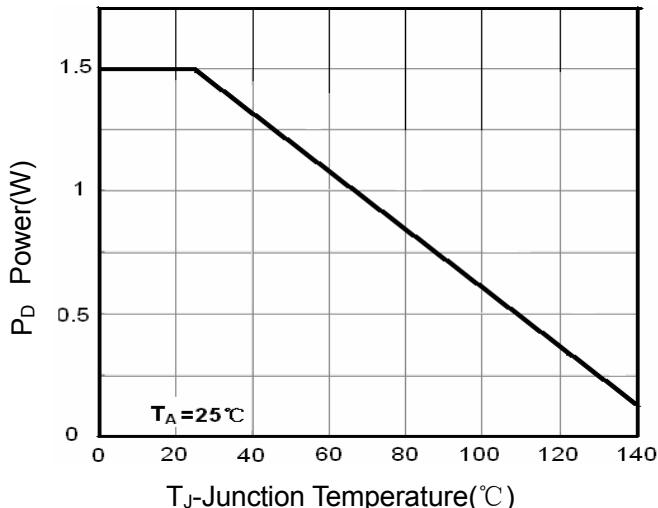


Figure 3 Power Dissipation

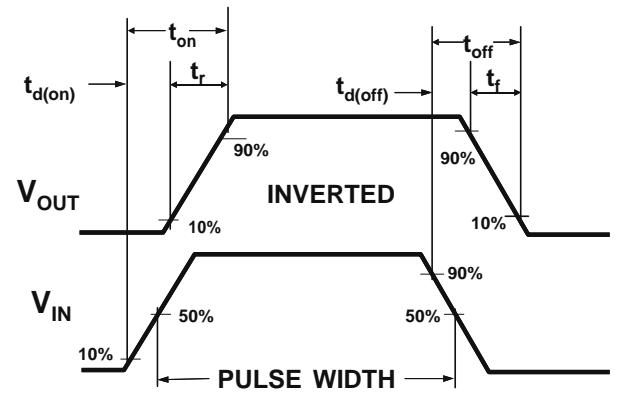


Figure 2:Switching Waveforms

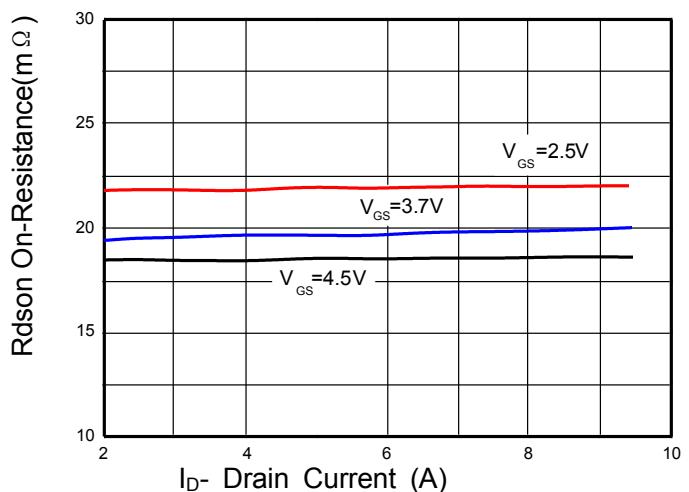


Figure 6 Drain-Source On-Resistance

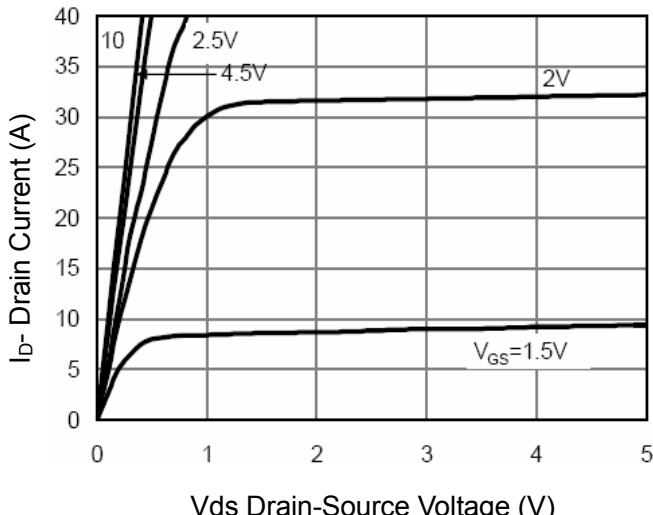


Figure 5 Output Characteristics

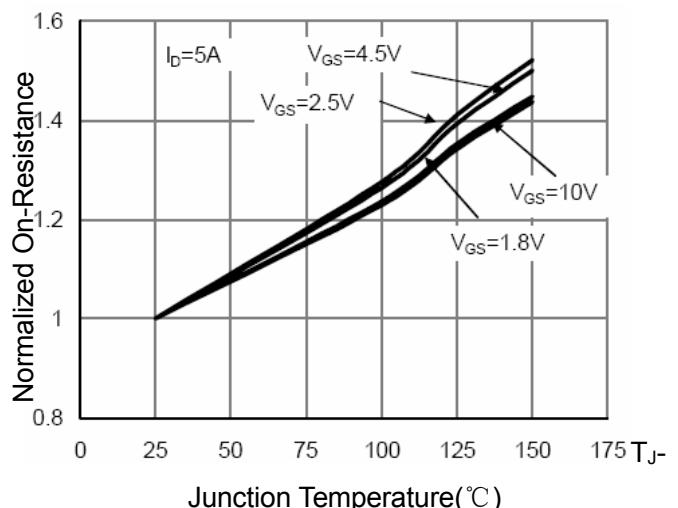


Figure 8 Drain-Source On-Resistance

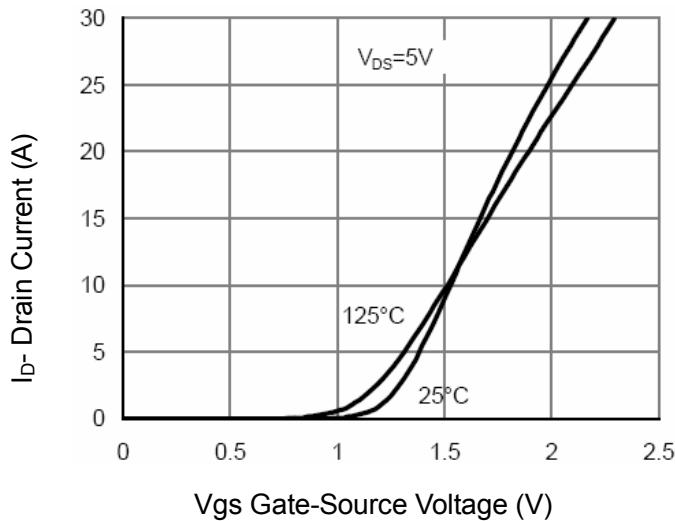


Figure 7 Transfer Characteristics

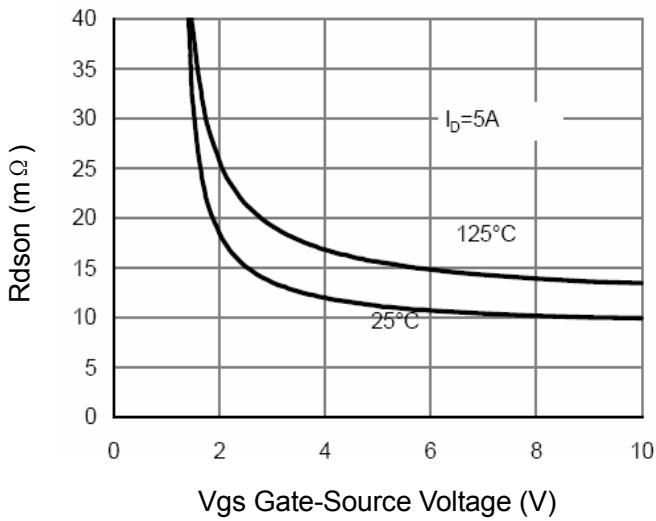


Figure 9 $R_{DS(on)}$ vs V_{GS}

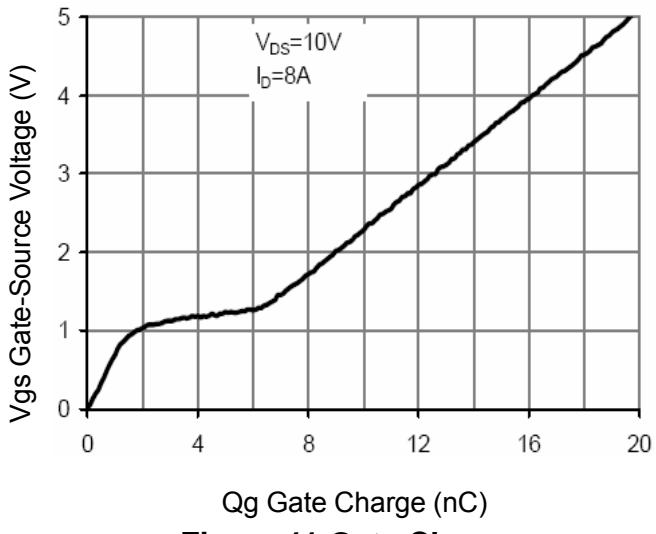


Figure 11 Gate Charge

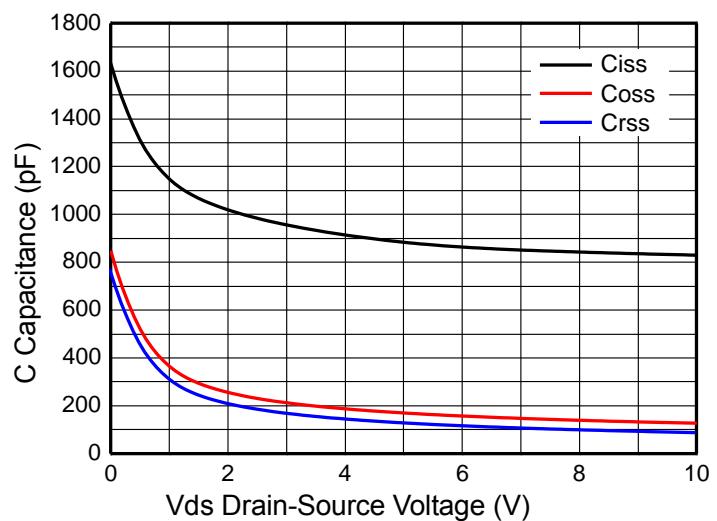


Figure 8 Capacitance vs V_{DS}

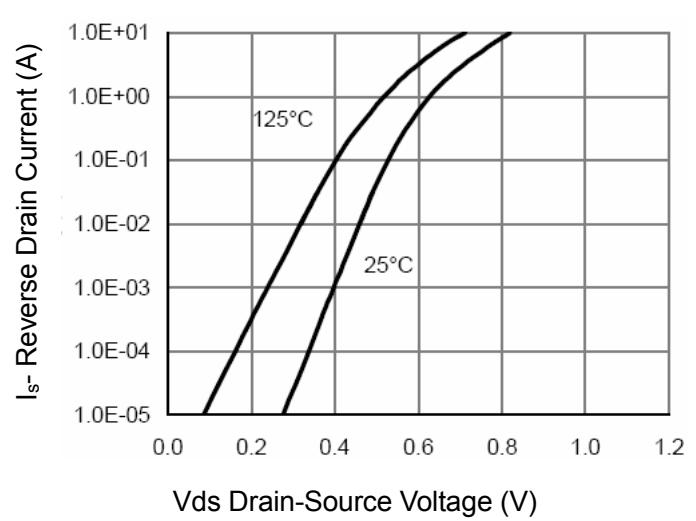


Figure 10 Capacitance vs V_{DS}

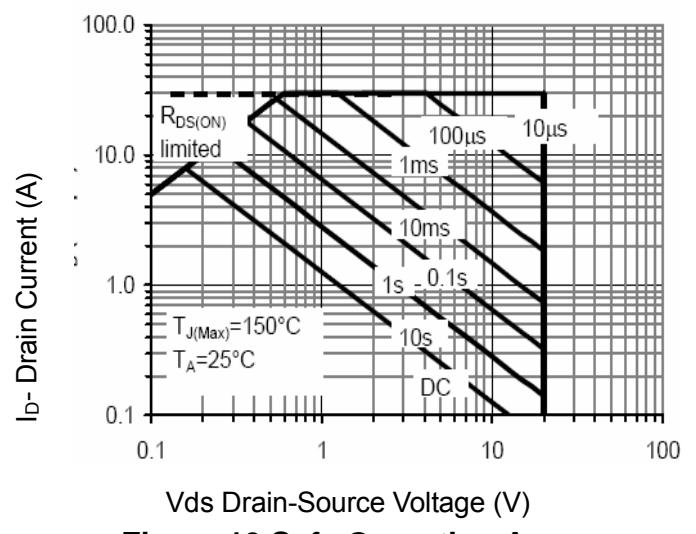
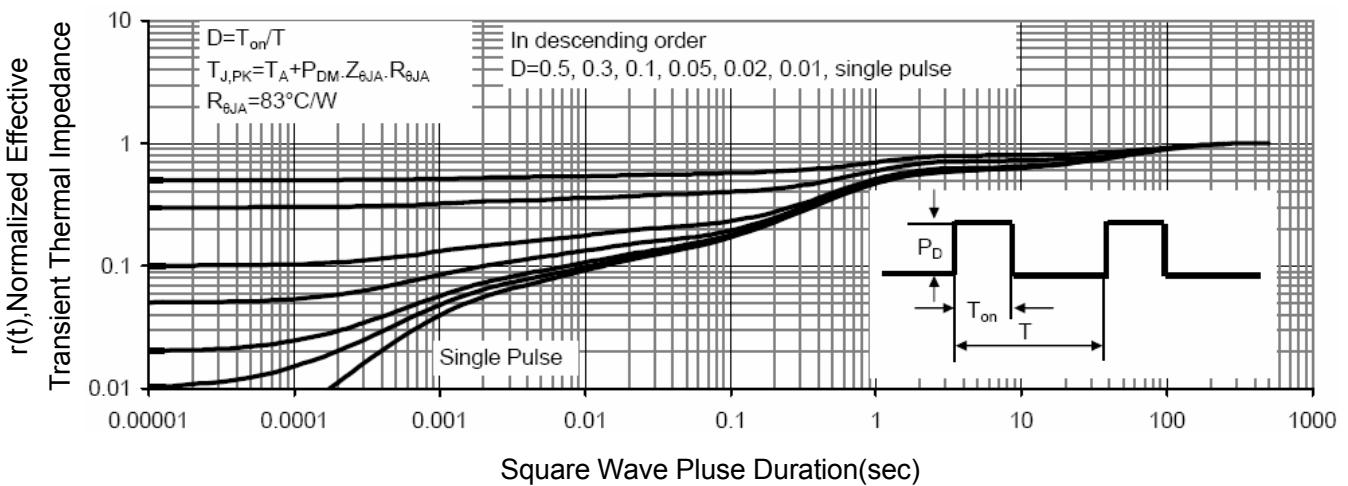
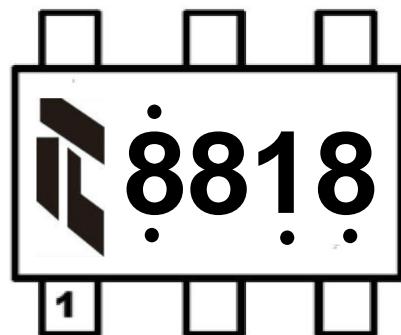


Figure 13 Safe Operation Area

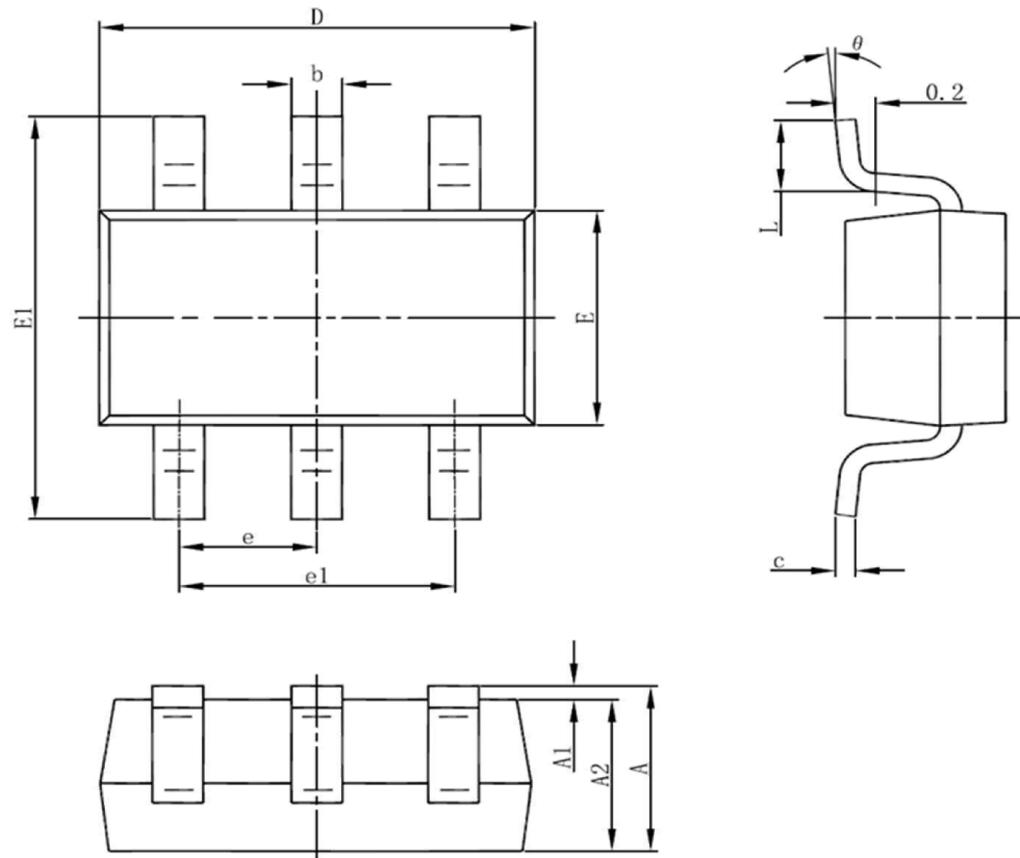
**Figure 14 Normalized Maximum Transient Thermal Impedance**

MARKING DESCRIPTION

SOT23-6

**Note:**

The printing points above and below the product model are the internal identification of the company. Each batch of products may be in different locations.

Package Information : SOT23-6

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°